Low Background Signal Electronics for the MAJORANA DEMONSTRATOR

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Office of Science





Outline



- The MAJORANA DEMONSTRATOR
 - Estimation of backgrounds
- Signal Electronics
 - Requirements
 - Front end boards
 - Signal Cables
- Signal Connectors
 - Original design
 - New Designs



MJD Overview

Funded by DOE Office of Nuclear Physics and NSF Particle Astrophysics, with additional contributions from international collaborators.

- Goals: Demonstrate backgrounds low enough to justify building a ton-scale ⁷⁶Ge experiment.
 - Establish feasibility to construct & field modular arrays of Ge detectors.
 - Searches for additional physics beyond the standard model
- Located underground at 4850' Sanford Underground Research Facility
- Background Goal in the 0vββ peak region of interest (4 keV at 2039 keV) 3 counts/ROI/t/y (after analysis cuts)

scales to 1 count/ROI/t/y for a ton-scale experiment

- 40-kg of Ge detectors
 - 30-kg of 87% enriched ⁷⁶Ge crystals & 10-kg of ^{nat}Ge
 - Detector Technology: P-type, point-contact.
- 2 independent cryostats
 - ultra-clean, electroformed Cu
 - 20 kg of detectors per cryostat
 - naturally scalable

Compact Shield

 low-background passive Cu and Pb shield with active muon veto



Background - Summary





Background Rate (c/ROI-t-y)

3/18/2015

Background Estimation



Perform radioassay of all materials that will go inside of shielding



γ-counting: Sensitivity ~mBq/kg

Neutron Activation Analysis (NAA): Sensitivity ~0.1 µBq/kg





Inductively Coupled Plasma Mass Spectrometry (ICP-MS): Sensitivity ~0.1 µBq/kg

> **Glow Discharge Mass Spectrometry (GDMS)**: Sensitivity ~0.1 µBq/kg



Background Estimation



Detailed model of geometry in Geant4 is used to estimate background detection efficiency for each component.

Background - Summary





Background Rate (c/ROI-t-y)

3/18/2015



Charge Sensitive Amplifier







Pulse travels up signal cables along string...















...along thermosyphon crossarm...







Requirements

- 1 channel for each detector
- 4 cables for each channel
- Low background materials
- Low mass
- Low noise
- Easy to manipulate in glove box
- Robust under vacuum and thermal cycling to LN temperature



Front end

Cable Pre-amplifier





Low Mass Front End (LMFE) JFET Amorphous (Ag epoxy) Au+Ti trace Ge Resistor Ag Epoxy Gate Pad 10104 **Fused silica** Capacitance **EFCu Spring** Wire bonds substrate from traces **Clip Mount** 10 GΩ 0.2 pF Feedback Source Det. Drain 0.05 pF Pulser

Low Mass Front End (LMFE)



U+Th activity from totaling components:

- 715 nBq/frontend
- 0.27 cts/ROI/t/y

Material	Assay Method	Isotope	purity	MJD BG
			[pg/g]	[c/ROI/t/y]
Fused Silica	ICP-MS	238 U	284	0.0616
		²³² Th	101	0.0259
aGe	ICP-MS	238 U	5000	0.0001
		²³² Th	5000	0.0001
Au	ICP-MS	238 U	2000	0.0015
		²³² Th	47000	0.0421
Ti	ICP-MS	^{238}U	< 100	~ 0
		²³² Th	$<\!400$	~ 0
FET die	ICP-MS	^{238}U	<141	< 0.0006
		²³² Th	$<\!2000$	< 0.0107
Al	ICP-MS	²³⁸ U	91000	0.0004
		232 Th	9.0	~ 0
Ag epoxy	γ -counting	238 U	<10000	< 0.0082
		²³² Th	<70000	< 0.0685
EFCu Spring Clip	ICP-MS	²³⁸ U	< 0.015	0.0005
		²³² Th	< 0.014	0.0003

ICP-MS of the full LMFE yields slightly higher U+Th backgrounds of

- 1590 nBq/frontend
- 0.6 cts/ROI/t/y



Signal Cables



Axon Picocoax[®] Cables

_extruded PFA _AWG50 bare copper _extruded PFA _bare copper

> 0.4mm OD 50Ω imp. 87 pF/m 0.4 g/m





Bundles of 4

U and Th backgrounds from ICP-MS 59 nBq/m 0.085 cts/ROI/t/y



Signal Connectors



Challenge: Most connectors use BeCu springs. BeCu is too radioactive for MJD!



Signal Connectors



Attempted Redesign: Paddle Comb



Plug Design



Contact force from Spring action of misaligned pins





Problems

 High Precision machining -> some pairings fail

Assay Limits



U and Th backgrounds from full body ICP-MS: 1521 nBq/connector 0.28 cts/ROI/t/y

Assay results consistent with connector activity dominated by pins



Material	Assay Method	Mass [g per pair]	Isotope	Activity [µBq/kg]	MJD BG [c/ROI/t/y]
Pins (w/BeCu)	ICP-MS	0.056	²³⁸ U 232m	795000 ± 12000	8.8 ± 0.1
Pins (no BeCu)	ICP-MS	0.056	²³⁸ U	41000 ± 1000 4600 ± 1500	$\frac{2.3 \pm 0.1}{0.05 \pm 0.02}$
Vernel CD 1		0.05	²³² Th 238U	$\frac{5800 \pm 100}{< 1000}$	$\frac{0.32 \pm 0.01}{< 0.20}$
vespel SP-1	NAA	0.95	²³² Th 238U	<12 5600 + 1000	< 0.01
Solder	GDMS	0.04	²³² Th	<12	<0.0004
Solder flux	GDMS	0.04	²³⁸ U ²³² Th	$\begin{array}{r}1200\pm200\\<400\end{array}$	$0.008 \pm 0.001 \\ < 0.016$

Electronics Production





EFCu and Vespel parts machined at 4850' level of SURF



Pins pressed into plug housing

Plugs are QC'd and soldered to cable bundles at UW

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Electronics Production



LMFEs are manufactured and attached to signal cables at LBNL



The MAJORANA Collaboration



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